

10/604,588

Customer No.: 31561
Docket No.: 10382-US-PA
Application No.: 10/604,588

Please amend paragraph [0030] of the specification as follows:

SPW
8/21/6
⁰⁰³⁴
[0030] Referring to FIG. 3, in order to obtain a balance between the difficulty of the driving process and the strength of the dielectric substrate 200a, the present flat lamp structure, as shown in FIG. 2, is supported on a carrier substrate 210, and the dielectric substrate 200a and the carrier substrate 210 are connected, for example, by means of an adhesive 208 or a plurality of adhesive means of 208 having a thickness between 0.1mm and 0.3mm. In accordance with the present invention, the adhesive 208 includes, for example, glass adhesive, UV curing adhesive or thermal curing adhesive.